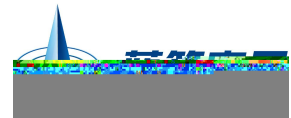
**修订记录**

A	2020.08.21		LRC-LMUN5314DW1T1G		
B	2021-11-25	6			



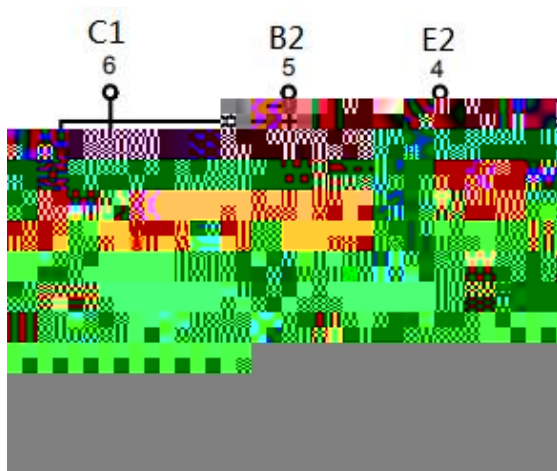
描述

SOT-363 NPN+PNP

Double silicon NPN and PNP transistor in a SOT-363 Plastic Package

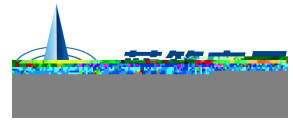
With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process, Halogen-free Product.

Switching applications, interface circuit and driver circuit applications.

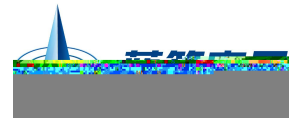


放大及印章代码

Marking	H314
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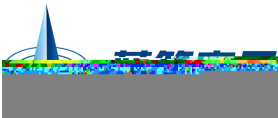


Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	50	

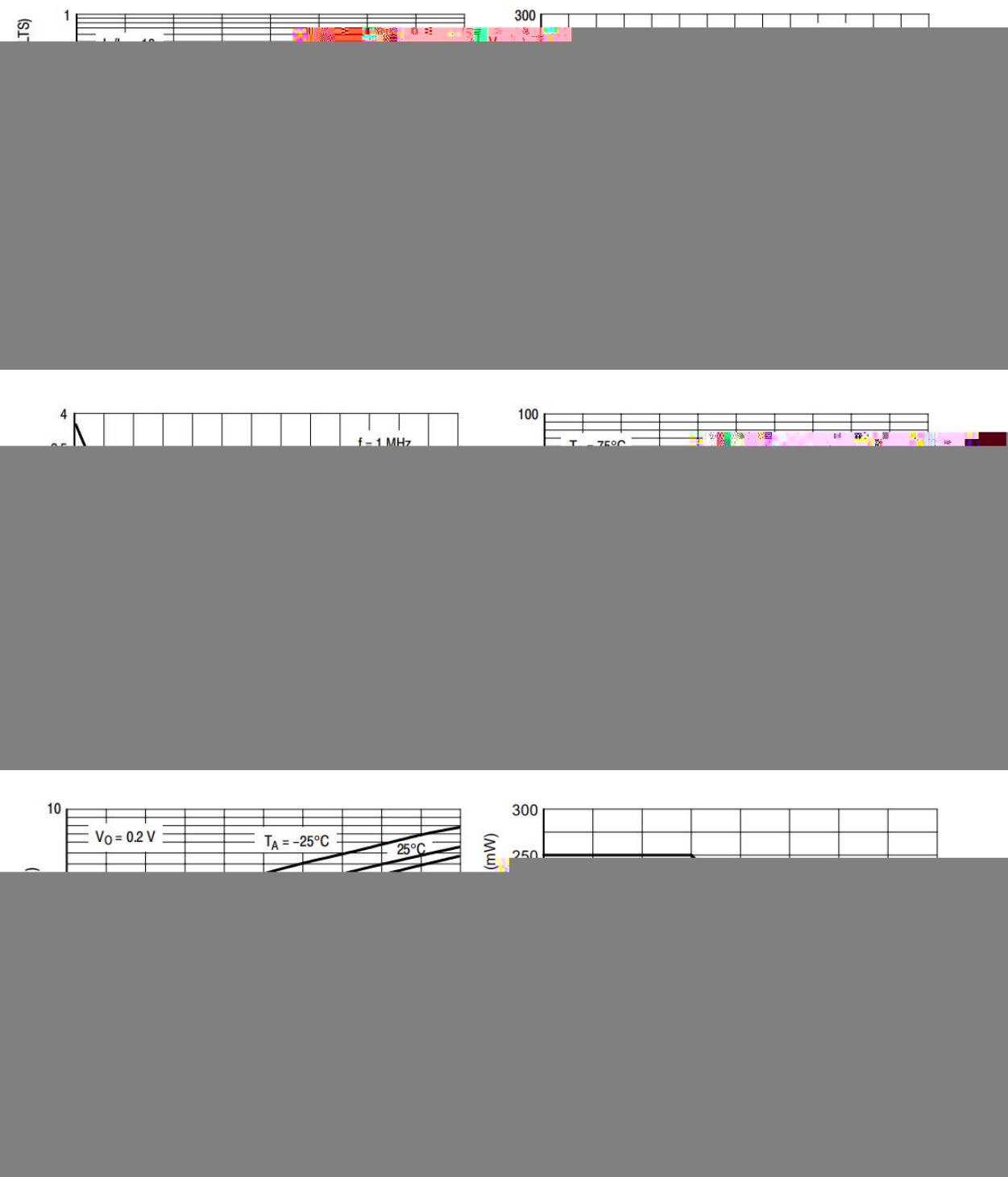


Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	-50	V
Input Voltage	V_{IN}	-40	V
		6.0	V
Output Current	I_C	-100	mA
	I_O	-70	mA
Power Dissipation	P_C	200	mW
	T_j	150	°C
	T_{stg}	-55~150	°C

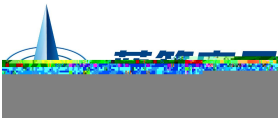
	Typ	Max	Unit
		0.3	V
			V



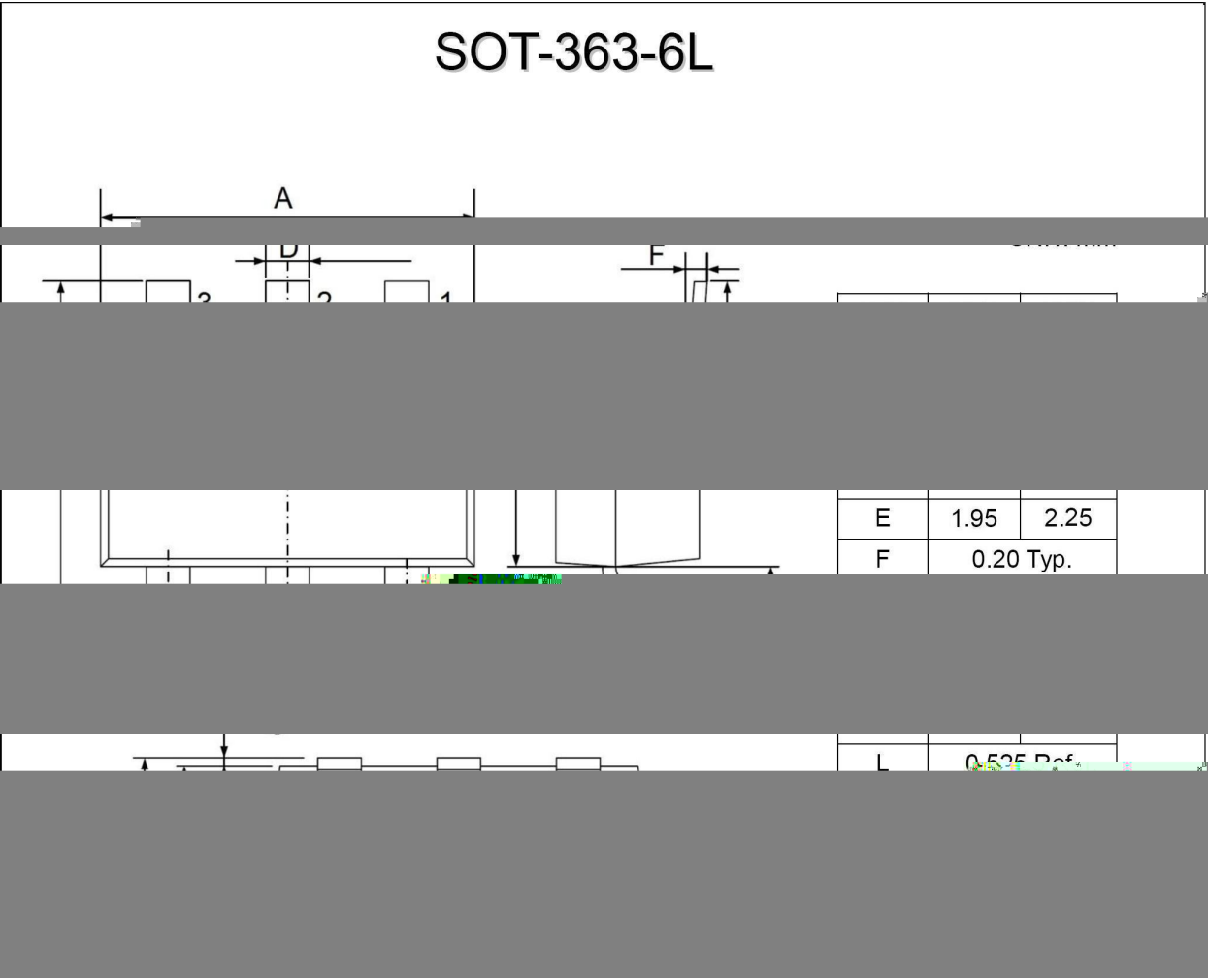
电参数曲线图

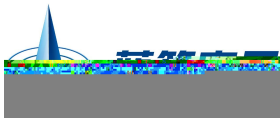


Rev.B Nov.-2021

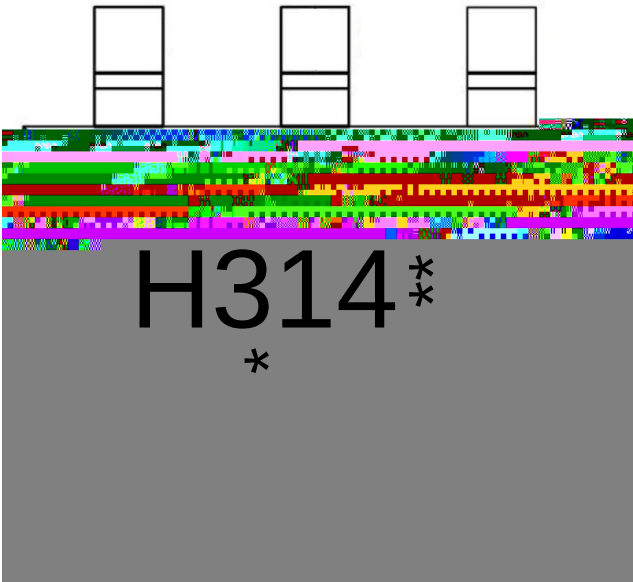


外形尺寸图

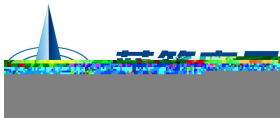




印章说明



- 1
- H314
- ***:
- Note:
- "1" Pin
- H314 Product Type Code
- ***: Lot No. Code, code change with Lot No.



回流焊温度曲线图 无铅 Temperature Profile for IR Reflow Soldering(Pb-Free)

1	150	180	60	90sec;	Note:	1.Preheating:150~180°C, Time:60~90sec.
2	245±5		5±0.5sec;			2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3		2	10°C/sec.			3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件

260±5°C	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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包装规格

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱